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(21)Application number : 07-037461 (71)Applicant : UBE IND LTD  
(22)Date of filing : 27.02.1995 (72)Inventor : INOUE HIROSHI  
TAKABAYASHI SEIICHIRO  
TANIOKA RIKIO

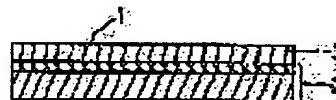
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## (54) METAL FOIL-LAMINATED POLYIMIDE FILM

### (57)Abstract:

PURPOSE: To integrally laminate a metal foil and a polyimide substrate layer with high adhesion by laying the metal foil over a multilayer polyimide thin film provided by integrally laminating thermoplastic aromatic polyimide layers of a low logarithmic viscosity on a side of a high temperature-resistant polyimide substrate layer, and then heating and pressurizing the layers.

CONSTITUTION: A multilayer polyimide film 2 of a metal foil-laminated polyimide film 1 is formed by coating at least one side of a high temperature-resistant aromatic polyimide substrate layer with a thin film formed by applying thereto a thermoplastic aromatic polyimide thin film by a coating method, and then drying and heating the laminate. The metal foil-laminated polyimide film 1 is formed by laying a metal foil on the thermoplastic aromatic polyimide thin film of the multilayer polyimide film 2 and then heating and pressuring them for lamination.



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